Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-18
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Material declaration form

ACTIVE: 9/20/2024

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H725ZGT3	281A*483XXXZ	A	9991	2024-09-18
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1290	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	20x20	144	Gull wing	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	**Description**	
,		

QueryList : REACH-27th June 2024				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**281A*483XXXZ**		1290.3446		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	16.077	mg	supplier	die	Silicon (Si)	7440-21-3		15.351	mg	954831	11896
				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	3179	40
				supplier	metallization	Copper (Cu)	7440-50-8		0.330	mg	20531	256
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	66	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.046	mg	2848	35
				supplier	metallization	Tungsten (W)	7440-33-7		0.148	mg	9206	115
				supplier	Passivation	Silicon Nitride	12033-89-5		0.038	mg	2384	30
				supplier	Passivation	Silicon Oxide	7631-86-9		0.112	mg	6954	87
Leadframe (C7025 + Ag)	Copper & its alloys	360.000	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		344.700	mg	957500	267138
				supplier	Leadframe	Nickel (Ni)	7440-02-0		10.728	mg	29800	8314
				supplier	Leadframe	Silicon (Si)	7440-21-3		2.340	mg	6500	1813
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.540	mg	1500	418
				supplier	Leadframe	Silver (Ag)	7440-22-4		1.692	mg	4700	1311
Glue Epoxy (EN-4900G)	Precious metals	2.768	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		2.090	mg	755000	1620
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.069	mg	25000	54
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.235	mg	85000	182
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.152	mg	55000	118
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.028	mg	10000	21
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.152	mg	55000	118
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.014	mg	5000	11
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.014	mg	5000	11
				supplier	Glue or tape	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.014	mg	5000	11
Bonding wire (Cu)	Precious metals	1.500	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		1.448	mg	965500	1122
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.047	mg	31000	36
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.005	mg	3500	4
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	895.000	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-d	85954-11-6		35.800	mg	40000	27745
				supplier	Molding Compound	Epoxy resin	Proprietary		17.900	mg	20000	13872
				supplier	Molding Compound	Phenol Resin	Proprietary		67.125	mg	75000	52021
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		635.003	mg	709500	492119
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		134.250	mg	150000	104042
				supplier	Molding Compound	Carbon black	1333-86-4		4.923	mg	5500	3815
External Plating (Sn)	M-011 Other inorganic materials	15.000	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		14.999	mg	999900	11624
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	1